



SD-106M-ACP11
W29.00xD28.50xH2.80

PIN 数(Number of contacts) : 9+2PIN

耐电压(Withstand voltage) : 250V AC for 1 min

操作方式(Operation mode): 自弹式/PUSH PUSH

操作寿命(Operation life): 5,000 Cycles Min

温度范围(Operating temp): -40°C TO +80°C

焊接温度(Welding temperature): 260±5° 5s

额定负荷(Rated load): 0.5A PERP IN.

焊接方式(Welding mode): 贴片式/SMT

接触电阻(Contact resistance): 100mΩ max.

包装方式(Packaging method): 卷带/Tape & Reel (TR)

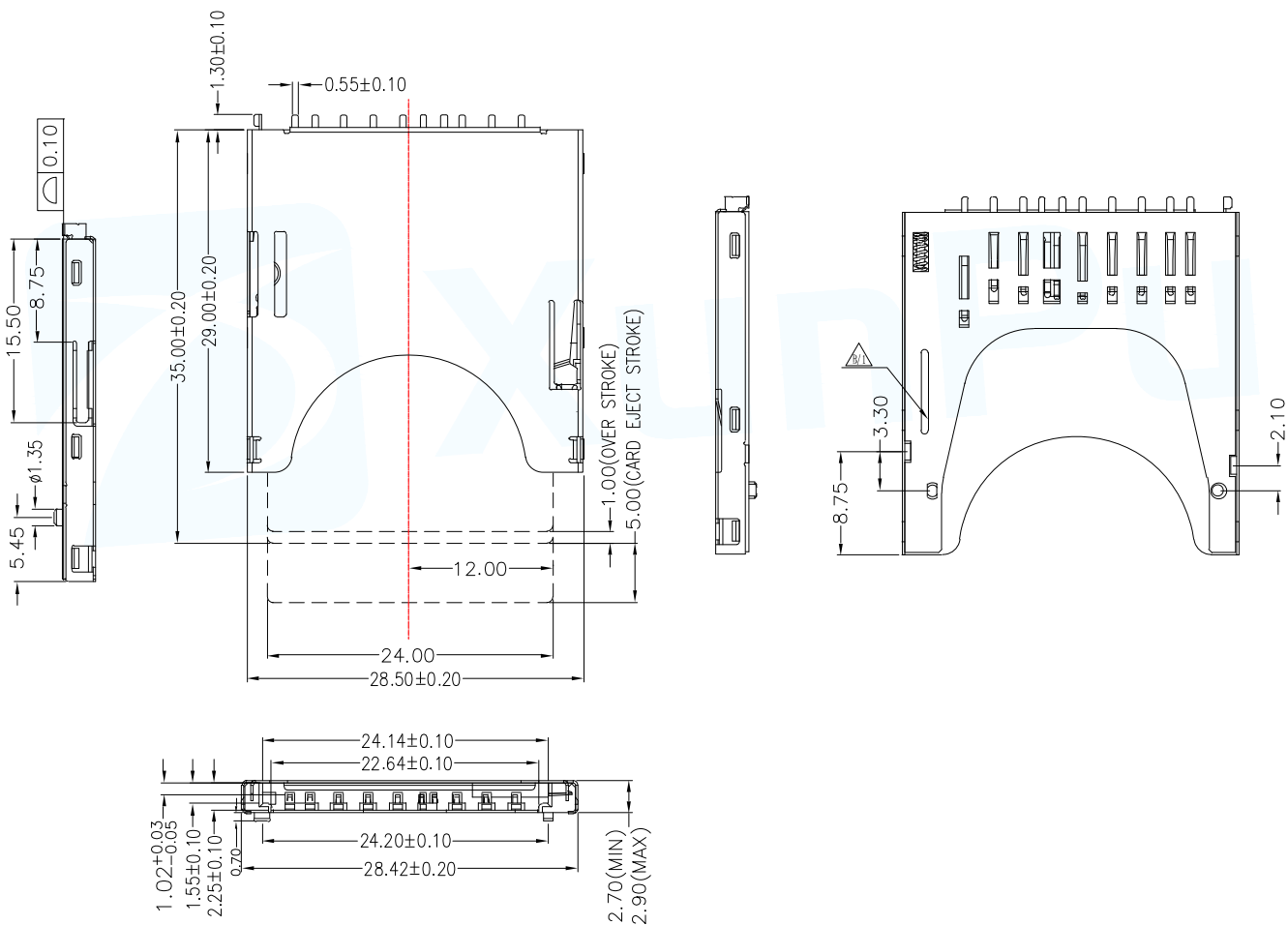
绝缘电阻(Insulation resistance): 1000MΩ min.

最小包装(Minimum packing): 350/PCS

外形尺寸 (UNIT:MM) / Size Chart

www.xunpudianzi.com

更多资料请参考技术选型档!



NOTES

1.MATERIAL

HOUSING: HIGH TEMPERATURE THERMOPLASTLC.

UL94V-0,COLOR:BLACK

CONTACT: COPPER ALLOY.

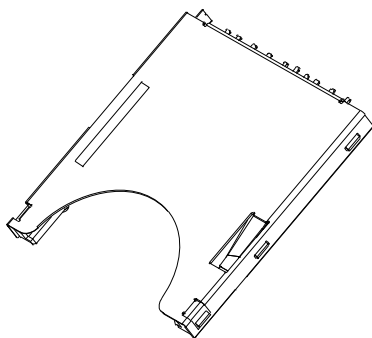
COVER: COPPER ALLOYS OR STEEL.

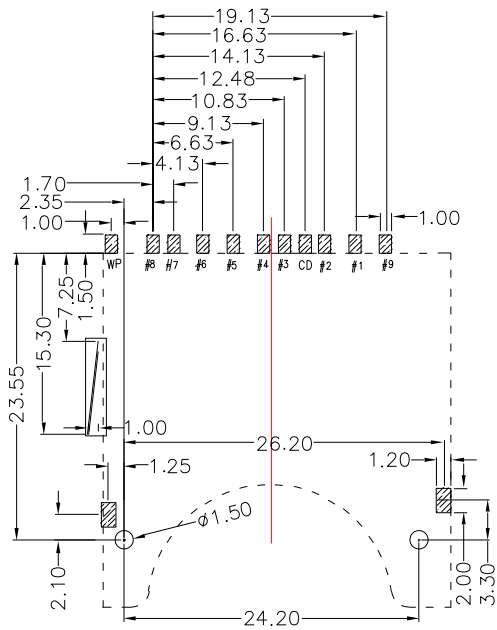
2.PLATING

UNDERPLATE: NICKEL.

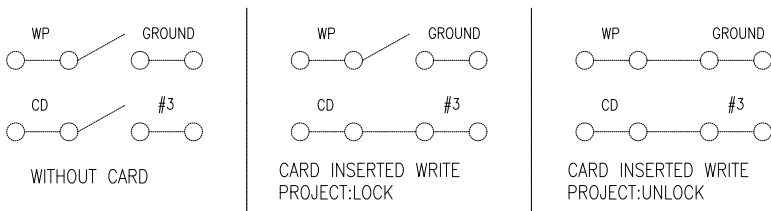
CONTACT AREA: GOLD OVER NICKEL.

SOLDER AREA: TIN OVER NICKEL.



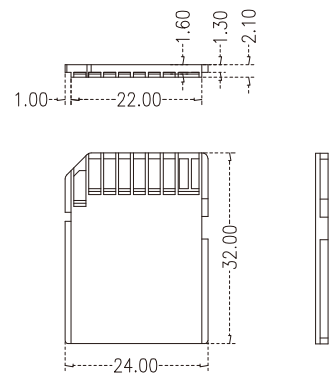


RECOMMENDED P.C.B LAYOUT
(General tolerance ± 0.05)



Circuit Diagram for Detect Switch

● SD CARD



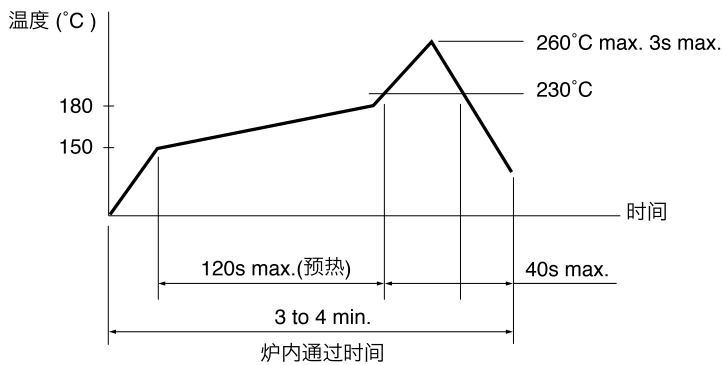
● 引脚定义/Pin Definition

PIN#	NAME	TYPE	DESCRIPTION
1#	CD/DAT3	I/O/PP	CARD DETECT/DATA LINE(BIT3)
2#	CMD	PP	COMMAND/RESPONSE
3#	VSS1	S	SUPPLY VOLTAGE GROUND
4#	VDD	S	SUPPLY VOLTAGE
5#	CLK	I	Clock
6#	VSS2	S	SUPPLY VOLTAGE GROUND
7#	DAT0	I/O/PP	DATA LINE(BIT0)
8#	DAT1	I/O/PP	DATA LINE(BIT1)
9#	DAT2	I/O/PP	DATA LINE(BIT2)

焊接条件 / Welding conditions

● 回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products
温度分布/Temperature distribution



● 手焊式/Hand welding

项目/Project	条件/condition
焊接温度 Welding temperature	350°C max.
持续焊接时间 Continuous welding time	3s max.
焊剂斗容量 Flux bucket capacity	60W max.

● 浸焊式/Immersion soldering

项目/Project	条件/condition
助焊剂附着量 Flux adhesion	不附着于零部件贴装面的程度 Not attached to the mounting surface of components
预热温度 Preheating temperature	印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max
预热温度时间 Preheat temperature time	60s max.
焊接温度 welding temperature	260°C max.
焊接浸渍时间 Welding immersion time	5s max.
焊接次数 Welding times	2 times max.

注:

1. 加热方式:以远红外线上下加热方式。
2. 温度测量:用 $\Phi 0.1\sim 0.2$ 的 CA(K)或 CC(T)测量位置在焊接连接部(锡/铜箔面)。
3. 固定方式:采用耐热胶带。